




ATCPZ003-MXHDM-T
Cust Spec, 8ld XDFN, I2C

<div><div>Microchip</div></div>			ATCPZ003-MXHDM-T Cust Spec, 8ld XDFN, I2C			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			J-STD-609A Product Marking and/or Pkg. Labeling e4		
Semiconductor Device Type:			QHB 008 XDFN 2x3x0.4mm NiPdAu											
Basic Substance		CAS Number	"Contained In" Sub-Component		% Total Weight	mg/part	ppm	2.14 (mg) Total		Mold Compound	% of Total Weight	47.25		
Silica Fused		60676-86-0	Mold Compound		41.708	1.889	417.076	Silica Fused		60676-86-0	88.27			
Epoxy Resin		Trade Secret	Mold Compound		2.948	0.134	29.484	Epoxy Resin		Trade Secret	6.24			
Phenol Resin		Trade Secret	Mold Compound		2.452	0.111	24.523	Phenol Resin		Trade Secret	5.19			
Carbon Black		1333-86-4	Mold Compound		0.142	0.006	1.418	Carbon Black		1333-86-4	0.30			
Copper		7440-50-8	Lead Frame		45.782	2.074	457.816	Total		100.00				
Nickel		7440-02-0	Lead Frame		1.428	0.065	14.277	2.16 (mg) Total		Lead Frame	% of Total Weight	47.59		
Silicon		7440-21-3	Lead Frame		0.309	0.014	3.093	Copper		7440-50-8	96.20			
Magnesium		7439-95-4	Lead Frame		0.071	0.003	714	Nickel		7440-02-0	3.00			
Silica, chemically prepared		7631-86-9	Die Attach		0.026	0.001	256	Silicon		7440-21-3	0.65			
acrylonitrile polymer		68610-41-3	Die Attach		0.012	0.001	116	Magnesium		7439-95-4	0.15			
Phenol formaldehyde resin		9003-35-4	Die Attach		0.001	0.000	14	Total		100.00				
Bisphenol A, epichlorohydrin polymer		25068-38-6	Die Attach		0.001	0.000	14	0.00 (mg) Total		Die Attach	% of Total Weight	0.04		
Silicon		7440-21-3	Chip (Die)		2.350	0.106	23.500	Silica, chemically prepared		7631-86-9	63.95			
Copper (Cu)		7440-50-8	Wire Bond		0.627	0.028	6.266	acrylonitrile polymer		68610-41-3	29.07			
Palladium (Pd)		744005-3	Wire Bond		0.013	0.001	128	Phenol formaldehyde resin		9003-35-4	3.49			
Silver (Ag)		7440-22-4	Wire Bond		0.001	0.000	6	Bisphenol A, epichlorohydrin polymer		25068-38-6	3.49			
Nickle (Ni)		7440-02-0	Plating on external leads (pins)		1.975	0.089	19.745	Total		100.00				
Palladium (Pd)		744005-3	Plating on external leads (pins)		0.138	0.006	1.385	0.11 Total (mg)		Chip (Die)	% of Total Weight	2.35		
Gold (Au)		7440-57-5	Plating on external leads (pins)		0.017	0.001	170	Doped Silicon		7440-21-3	100.00			
TOTALS:					100.000	4.530	1,000,000	Total		100.00				
0.00453 g Total Mass														
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)														
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.														
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.														
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://iq.ul.com/plastics/														
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table														